

CY WIRELESS TECHNOLOGY LIMITED

SPECIFICATION FOR APPROVAL

CUSTOMER	
NOMINAL FREQUENCY	13.52127MHz
HOLDER TYPE	3225
SPEC. NO. (P/N)	13.52127S3
CUSTOMER P/N	
ISSUE DATE	

Add: 1407, Block C, Tairan Building, 8th Tairan Road, Futian District, Shenzhen, Guangdong, China

TEL: 0086-755-23937707 FAX: 0086-755-88351759

www.rficy.com

1. ELECTRICAL SPECIFICATIONS

Parts Number : <u>13.52127S3</u>

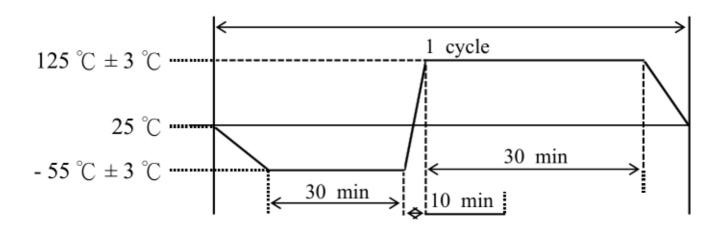
T4	C1	Specifications			200	
Item	Symbol-	Min	Type	Max	Units	Notes
Nominal frequency	FO	13.521270			MHz	
Mode of Oscillation	от	Fundamental				
Load Capacitance	LC	10			pF	
Frequency Tolerance	FT	± 15			ppm	at 25°C ± 3°C
Frequency Stability		± 20			ppm	with working temperature Reference to 25℃
Working temperature range	TR	-20~70		°C		
Drive Level	DL	100		μW	Max.	
Series Resonant Resistance RR	CI/RR	60		Ω	Max.	
Insulation Resistance	IR	>500		МΩ	3) 	
Shunt Capacitance C0	C0	7		pF		
Aging		3		ppm/yr.		
Storage temperature range		-	55 ~ 125	i	°	
Unit Weight					g	

2. MARKING

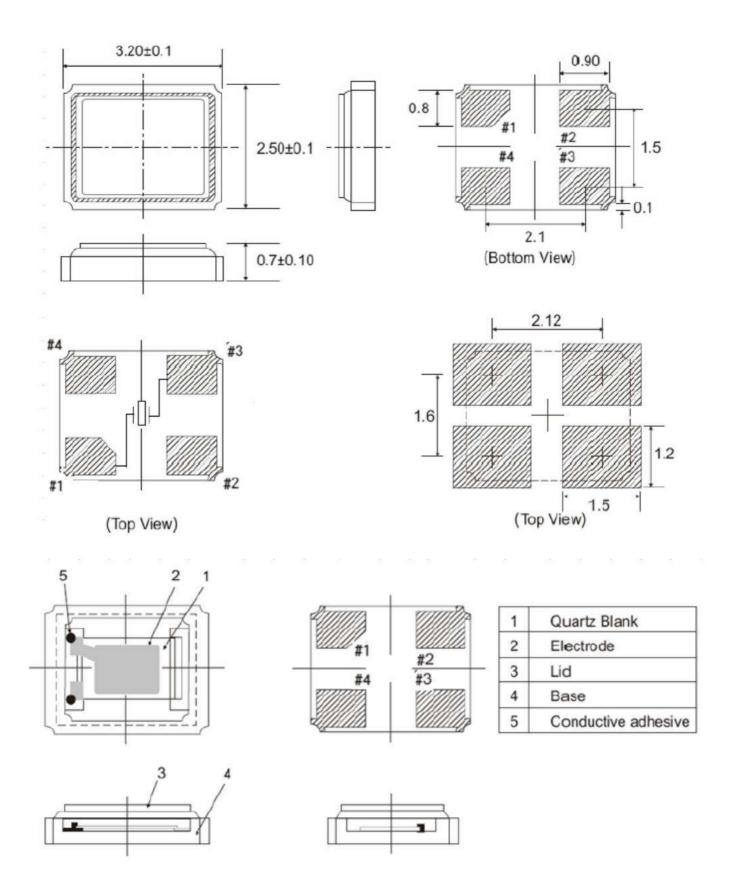
13.52127S3

3. RELIABILITY SPECIFICATIONS

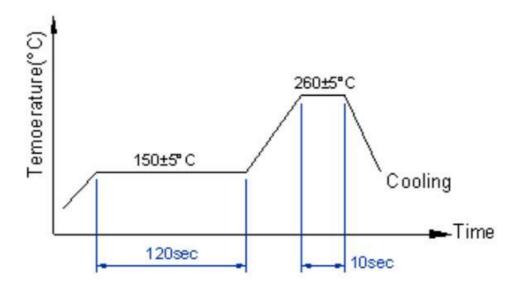
NO.	TEST ITEM	TEST METHODS			
1	DROP TEST	Device are dropped from a height of 150 cm onto 2 mm thickness stainless plate executing 3 times of random drops.			
2	MECHANICAL SHOCK	Device are shocked to half sine wave (1000 G) three mutually perpendicular axes each 3 times.			
		Frequency range	10 ~ 2000 Hz		
		Amplitude	1.5 mm		
3 VIBRATI	VIBRATION	Sweep Time	20 minute		
		Test Time	2 hours		
		MIL - STD - 20E Method 208C			
	Temperature	245°C±5°C			
		Material	H63A (Silver 2 ~ 3 %)		
4 SOLDERABILITY		Immersion depth	0.5 mm minimum		
		Immersion time	3 ± 0.5 seconds		
		Flux	Rosin resin methyl alcohol		
			solvent (1:4)		
5	RESISTANCE TO	MIL - SLD -202, Method 210, Condition I or J 10 sec			
	SOLDERING HEAT	immersion into 260 ± 5 °C solder pot, above 180 °C is			
		90 ~ 120 sec.			
6	LOW TEMP. STORAGE	Leave at - 55 °C \pm 2°C for 1000 ± 12 hours			
7	HIGH TEMP. STORAGE	Leave at $125 ^{\circ}\text{C} \pm 2 ^{\circ}\text{C}$ for 1000 ± 12 hours			
8	THERMAL SHOCK	Total 100 cycles of the following temperature cycle			



4. DIMENSIONS

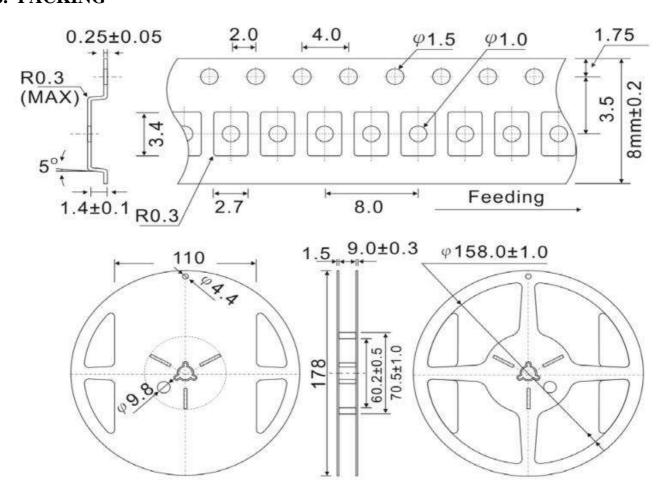


5. SUGGESTED IR REFLOW PROFILE



Total Time: 200 Sec.Max Solder melting point: 185°C

6. PACKING



- 1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
- 2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

